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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A53 MPCore™ with CoreSight™, Dual ARM®Cortex™-R5 with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	500MHz, 1.2GHz
Primary Attributes	Zynq®UltraScale+™ FPGA, 192K+ Logic Cells
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	900-BBGA, FCBGA
Supplier Device Package	900-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xczu4cg-1fbvb900e

Available Speed Grades and Operating Voltages

Table 3 describes the speed grades per device and the V_{CCINT} operating supply voltages for the full-power, low-power, and DDR domains. For more information on selecting devices and speed grades, see the *UltraScale Architecture and Product Overview* (DS890).

Table 3: Available Speed Grades and Operating Voltages

Speed Grade	V_{CCINT}	$V_{CC_PSINTLP}$	$V_{CC_PSINTFP}$	$V_{CC_PSINTFP_DDR}$	Units
-3E	0.90	0.90	0.90	0.90	V
-2E	0.85	0.85	0.85	0.85	V
-2I	0.85	0.85	0.85	0.85	V
-2LE	0.85	0.85	0.85	0.85	V
-1E	0.85	0.85	0.85	0.85	V
-1I	0.85	0.85	0.85	0.85	V
-1LI	0.85	0.85	0.85	0.85	V
-2LE	0.72	0.85	0.85	0.85	V
-1LI	0.72	0.85	0.85	0.85	V

DC Characteristics Over Recommended Operating Conditions

Table 4: DC Characteristics Over Recommended Operating Conditions

Symbol	Description	Min	Typ ⁽¹⁾	Max	Units
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data might be lost).	0.68	–	–	V
V_{DRAUX}	Data retention V_{CCAUX} voltage (below which configuration data might be lost).	1.5	–	–	V
I_{REF}	V_{REF} leakage current per pin.	–	–	15	μ A
I_L	Input or output leakage current per pin (sample-tested). ⁽²⁾	–	–	15	μ A
C_{IN} ⁽³⁾	Die input capacitance at the pad (HP I/O).	–	–	3.1	pF
	Die input capacitance at the pad (HD I/O).	–	–	4.75	pF
I_{RPU}	Pad pull-up (when selected) at $V_{IN} = 0V$, $V_{CCO} = 3.3V$.	75	–	190	μ A
	Pad pull-up (when selected) at $V_{IN} = 0V$, $V_{CCO} = 2.5V$.	50	–	169	μ A
	Pad pull-up (when selected) at $V_{IN} = 0V$, $V_{CCO} = 1.8V$.	60	–	120	μ A
	Pad pull-up (when selected) at $V_{IN} = 0V$, $V_{CCO} = 1.5V$.	30	–	120	μ A
	Pad pull-up (when selected) at $V_{IN} = 0V$, $V_{CCO} = 1.2V$.	10	–	100	μ A
I_{RPD}	Pad pull-down (when selected) at $V_{IN} = 3.3V$.	60	–	200	μ A
	Pad pull-down (when selected) at $V_{IN} = 1.8V$.	29	–	120	μ A
$I_{CCADCONPL}$	Analog supply current for the PL SYSMON circuits in the power-up state.	–	–	8	mA
$I_{CCADCONPS}$	Analog supply current for the PS SYSMON circuits in the power-up state.	–	–	10	mA
$I_{CCADCOFFPL}$	Analog supply current for the PL SYSMON circuits in the power-down state.	–	–	1.5	mA
$I_{CCADCOFFPS}$	Analog supply current for the PS SYSMON circuits in the power-down state.	–	–	1.8	mA

V_{IN} Maximum Allowed AC Voltage Overshoot and Undershoot

Table 6: V_{IN} Maximum Allowed AC Voltage Overshoot and Undershoot for HD I/O Banks⁽¹⁾

AC Voltage Overshoot	% of UI at -40°C to 100°C	AC Voltage Undershoot	% of UI at -40°C to 100°C
$V_{CCO} + 0.30$	100%	-0.30	100%
$V_{CCO} + 0.35$	100%	-0.35	90%
$V_{CCO} + 0.40$	100%	-0.40	78%
$V_{CCO} + 0.45$	100%	-0.45	40%
$V_{CCO} + 0.50$	100%	-0.50	24%
$V_{CCO} + 0.55$	100%	-0.55	18.0%
$V_{CCO} + 0.60$	100%	-0.60	13.0%
$V_{CCO} + 0.65$	100%	-0.65	10.8%
$V_{CCO} + 0.70$	92%	-0.70	9.0%
$V_{CCO} + 0.75$	92%	-0.75	7.0%
$V_{CCO} + 0.80$	92%	-0.80	6.0%
$V_{CCO} + 0.85$	92%	-0.85	5.0%
$V_{CCO} + 0.90$	92%	-0.90	4.0%
$V_{CCO} + 0.95$	92%	-0.95	2.5%

Notes:

1. A total of 200 mA per bank should not be exceeded.

Table 7: V_{IN} Maximum Allowed AC Voltage Overshoot and Undershoot for HP I/O Banks⁽¹⁾⁽²⁾

AC Voltage Overshoot	% of UI at -40°C to 100°C	AC Voltage Undershoot	% of UI at -40°C to 100°C
$V_{CCO} + 0.30$	100%	-0.30	100%
$V_{CCO} + 0.35$	100%	-0.35	100%
$V_{CCO} + 0.40$	92%	-0.40	92%
$V_{CCO} + 0.45$	50%	-0.45	50%
$V_{CCO} + 0.50$	20%	-0.50	20%
$V_{CCO} + 0.55$	10%	-0.55	10%
$V_{CCO} + 0.60$	6%	-0.60	6%
$V_{CCO} + 0.65$	2%	-0.65	2%
$V_{CCO} + 0.70$	2%	-0.70	2%

Notes:

1. A total of 200 mA per bank should not be exceeded.
2. For UI smaller than 20 μs .

Table 19: Complementary Differential SelectIO DC Input and Output Levels for HP I/O Banks⁽¹⁾

I/O Standard	V _{ICM} (V) ⁽²⁾			V _{ID} (V) ⁽³⁾		V _{OL} (V) ⁽⁴⁾	V _{OH} (V) ⁽⁵⁾	I _{OL}	I _{OH}
	Min	Typ	Max	Min	Max	Max	Min	mA	mA
DIFF_HSTL_I	0.680	V _{CCO} /2	(V _{CCO} /2) + 0.150	0.100	–	0.400	V _{CCO} – 0.400	5.8	–5.8
DIFF_HSTL_I_12	0.400 x V _{CCO}	V _{CCO} /2	0.600 x V _{CCO}	0.100	–	0.250 x V _{CCO}	0.750 x V _{CCO}	4.1	–4.1
DIFF_HSTL_I_18	(V _{CCO} /2) – 0.175	V _{CCO} /2	(V _{CCO} /2) + 0.175	0.100	–	0.400	V _{CCO} – 0.400	6.2	–6.2
DIFF_HSUL_12	(V _{CCO} /2) – 0.120	V _{CCO} /2	(V _{CCO} /2) + 0.120	0.100	–	20% V _{CCO}	80% V _{CCO}	0.1	–0.1
DIFF_SSTL12	(V _{CCO} /2) – 0.150	V _{CCO} /2	(V _{CCO} /2) + 0.150	0.100	–	(V _{CCO} /2) – 0.150	(V _{CCO} /2) + 0.150	8.0	–8.0
DIFF_SSTL135	(V _{CCO} /2) – 0.150	V _{CCO} /2	(V _{CCO} /2) + 0.150	0.100	–	(V _{CCO} /2) – 0.150	(V _{CCO} /2) + 0.150	9.0	–9.0
DIFF_SSTL15	(V _{CCO} /2) – 0.175	V _{CCO} /2	(V _{CCO} /2) + 0.175	0.100	–	(V _{CCO} /2) – 0.175	(V _{CCO} /2) + 0.175	10.0	–10.0
DIFF_SSTL18_I	(V _{CCO} /2) – 0.175	V _{CCO} /2	(V _{CCO} /2) + 0.175	0.100	–	(V _{CCO} /2) – 0.470	(V _{CCO} /2) + 0.470	7.0	–7.0

Notes:

1. DIFF_POD10 and DIFF_POD12 HP I/O bank specifications are shown in Table 20, Table 21, and Table 22.
2. V_{ICM} is the input common mode voltage.
3. V_{ID} is the input differential voltage.
4. V_{OL} is the single-ended low-output voltage.
5. V_{OH} is the single-ended high-output voltage.

Table 20: DC Input Levels for Differential POD10 and POD12 I/O Standards⁽¹⁾⁽²⁾

I/O Standard	V _{ICM} (V)			V _{ID} (V)	
	Min	Typ	Max	Min	Max
DIFF_POD10	0.63	0.70	0.77	0.14	–
DIFF_POD12	0.76	0.84	0.92	0.16	–

Notes:

1. Tested according to relevant specifications.
2. Standards specified using the default I/O standard configuration. For details, see the *UltraScale Architecture SelectIO Resources User Guide* (UG571).

Table 21: DC Output Levels for Single-ended and Differential POD10 and POD12 Standards⁽¹⁾⁽²⁾

Symbol	Description	V _{OUT}	Min	Typ	Max	Units
R _{OL}	Pull-down resistance.	V _{OM_DC} (as described in Table 22)	36	40	44	Ω
R _{OH}	Pull-up resistance.	V _{OM_DC} (as described in Table 22)	36	40	44	Ω

Notes:

1. Tested according to relevant specifications.
2. Standards specified using the default I/O standard configuration. For details, see the *UltraScale Architecture SelectIO Resources User Guide* (UG571).

Table 22: Table 21 Definitions for DC Output Levels for POD Standards

Symbol	Description	All Speed Grades	Units
V _{OM_DC}	DC output Mid measurement level (for IV curve linearity).	0.8 x V _{CCO}	V

Table 26: Speed Grade Designations by Device (Cont'd)

Device	Speed Grade, Temperature Ranges, and V _{CCINT} Operating Voltages		
	Advance	Preliminary	Production
XCZU5EG	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU5EV	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU6CG	-2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)
XCZU6EG	-3E (V _{CCINT} = 0.90V) -2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)
XCZU7CG	-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU7EG	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU7EV	-3E (V _{CCINT} = 0.90V), -2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V), -2LE (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V), -1I (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V), -1LI (V _{CCINT} = 0.72V)		
XCZU9CG	-2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)
XCZU9EG	-3E (V _{CCINT} = 0.90V) -2LE (V _{CCINT} = 0.85V) -2LE (V _{CCINT} = 0.72V) -1LI (V _{CCINT} = 0.85V) -1LI (V _{CCINT} = 0.72V)		-2E (V _{CCINT} = 0.85V) -2I (V _{CCINT} = 0.85V) -1E (V _{CCINT} = 0.85V) -1I (V _{CCINT} = 0.85V)

Production Silicon and Software Status

In some cases, a particular family member (and speed grade) is released to production before a speed specification is released with the correct label (Advance, Preliminary, Production). Any labeling discrepancies are corrected in subsequent speed specification releases.

Table 27 lists the production released Zynq UltraScale+ MPSoC, speed grade, and the minimum corresponding supported speed specification version and Vivado software revisions. The Vivado software and speed specifications listed are the minimum releases required for production. All subsequent releases of software and speed specifications are valid.

Table 27: Zynq UltraScale+ MPSoC Device Production Software and Speed Specification Release

Device	Speed Grade and V _{CCINT} Operating Voltages						
	0.90V	0.85V				0.72V	
	-3	-2	-1	-2L	-1L	-2L	-1L
XCZU2CG	N/A	Vivado tools 2017.1 v1.10					
XCZU2EG	N/A	Vivado tools 2017.1 v1.10					
XCZU3CG	N/A	Vivado tools 2017.1 v1.10					
XCZU3EG	N/A	Vivado tools 2017.1 v1.10					
XCZU4CG	N/A						
XCZU4EG							
XCZU4EV							
XCZU5CG	N/A						
XCZU5EG							
XCZU5EV							
XCZU6CG	N/A	Vivado tools 2017.1 v1.10					
XCZU6EG		Vivado tools 2017.1 v1.10					
XCZU7CG	N/A						
XCZU7EG							
XCZU7EV							
XCZU9CG	N/A	Vivado tools 2017.1 v1.10					
XCZU9EG		Vivado tools 2017.1 v1.10					
XCZU11EG							
XCZU15EG							
XCZU17EG							
XCZU19EG							

Notes:

1. See Table 3 for the complete list of operating voltages by speed grade.
2. Blank entries indicate a device and/or speed grade in Advance or Preliminary status.

Table 30: PS DDR Performance (Cont'd)

Memory Standard	Package	DRAM Type	Speed Grade						Units
			-3		-2		-1		
			Min	Max	Min	Max	Min	Max	
DDR3	All FFV packages, FBVB900 and SFVC784	Single rank component	664	2133	664	2133	664	2133	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1866	664	1866	664	1866	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1600	664	1600	664	1600	Mb/s
	SFVA625	Single rank component	664	1866	664	1866	664	1866	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1600	664	1600	664	1600	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1333	664	1333	664	1333	Mb/s
	SBVA484	Single rank component	664	1066	664	1066	664	1066	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1066	664	1066	664	1066	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1066	664	1066	664	1066	Mb/s
DDR3L	All FFV packages, FBVB900 and SFVC784	Single rank component	664	1866	664	1866	664	1866	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1600	664	1600	664	1600	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1333	664	1333	664	1333	Mb/s
	SFVA625	Single rank component	664	1600	664	1600	664	1600	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1333	664	1333	664	1333	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1066	664	1066	664	1066	Mb/s
	SBVA484	Single rank component	664	1066	664	1066	664	1066	Mb/s
		1 rank DIMM ⁽¹⁾⁽²⁾	664	1066	664	1066	664	1066	Mb/s
		2 rank DIMM ⁽¹⁾⁽³⁾	664	1066	664	1066	664	1066	Mb/s
LPDDR3	All FFV packages, FBVB900 and SFVC784	Single die package ⁽⁶⁾	664	1600	664	1600	664	1600	Mb/s
		Dual die package ⁽⁶⁾	664	1333	664	1333	664	1333	Mb/s
	SFVA625	Single die package ⁽⁶⁾	664	1333	664	1333	664	1333	Mb/s
		Dual die package ⁽⁶⁾	664	1066	664	1066	664	1066	Mb/s
	SBVA484	Single die package ⁽⁶⁾	664	1066	664	1066	664	1066	Mb/s
		Dual die package ⁽⁶⁾	664	1066	664	1066	664	1066	Mb/s

Notes:

1. Dual in-line memory module (DIMM) includes RDIMM, SODIMM, and UDIMM.
2. Includes: 1 rank 1 slot, dual-die package 2 rank.
3. Includes: 2 rank 1 slot.
4. Dual die package includes single die with ECC.
5. LPDDR4 support is only available as a 32-bit interface.
6. 64-bit LPDDR3 interface performance values are defined without ECC support.

PS Gigabit Ethernet Controller Interface

 Table 44: RGMII Interface⁽¹⁾

Symbol	Description	Min	Max	Units
T _{DCGEMTXCLK}	Transmit clock duty cycle.	45	55	%
T _{GEMTXCKO}	TXD output clock to out time.	-0.5	0.5	ns
T _{GEMRXDCK}	RXD input setup time.	0.8	-	ns
T _{GEMRXCKD}	RXD input hold time.	0.8	-	ns
T _{MDIOCLK}	MDC output clock period.	400	-	ns
T _{MDIOCKL}	MDC low time.	160	-	ns
T _{MDIOCKH}	MDC high time.	160	-	ns
T _{MDIODCK}	MDIO input data setup time.	80	-	ns
T _{MDIOCKD}	MDIO input data hold time.	0.0	-	ns
T _{MDIOCKO}	MDIO output data delay time.	-1.0	15	ns
F _{GETXCLK}	RGMII_TX_CLK transmit clock frequency.	-	125	MHz
F _{GERXCLK}	RGMII_RX_CLK receive clock frequency.	-	125	MHz
F _{ENET_REF_CLK}	Ethernet reference clock frequency.	-	125	MHz

Notes:

1. The test conditions are configured to the LVCMOS 2.5V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.

PS SD/SDIO Controller Interface

 Table 45: SD/SDIO Interface⁽¹⁾

Symbol	Description	Min	Max	Units
SD/SDIO Interface DDR50 Mode				
T _{DCDDRCLK}	SD device clock duty cycle.	45	55	%
T _{SDDDRCKO1}	Clock to output delay, data. ⁽²⁾	1.0	6.8	ns
T _{SDDRIVW}	Input valid data window. ⁽³⁾	3.5	-	ns
T _{SDDDRDCK2}	Input setup time, command.	4.7	-	ns
T _{SDDDRCKD2}	Input hold time, command.	1.5	-	ns
T _{SDDDRCKO2}	Clock to output delay, command.	1.0	13.8	ns
F _{SDDDRCLK}	High-speed mode SD device clock frequency.	-	50	MHz
SD/SDIO Interface SDR104				
T _{DCSDHCLK1}	SD device clock duty cycle.	40	60	%
T _{SSDRCKO1}	Clock to output delay, all outputs. ⁽²⁾	1.0	3.2	ns
T _{SSDR1IVW}	Input valid data window. ⁽³⁾	0.5	-	UI
F _{SSDRCLK1}	SDR104 mode device clock frequency.	-	200	MHz
SD/SDIO Interface SDR50/25				
T _{DCSDHCLK2}	SD device clock duty cycle.	40	60	%
T _{SSDRCKO2}	Clock to output delay, all outputs. ⁽²⁾	1.0	6.8	ns
T _{SSDR2IVW}	Input valid data window. ⁽³⁾	0.3	-	UI

PS I2C Controller Interface

Table 47: I2C Interface⁽¹⁾

Symbol	Description	Min	Max	Units
I2C Fast-mode Interface				
$T_{I2CFCKL}$	SCL Low time.	1.3	–	μ s
$T_{I2CFCKH}$	SCL High time.	0.6	–	μ s
$T_{I2CFCKO}$	SDA clock to out delay.	–	900	ns
$T_{I2CFDCK}$	SDA input setup time.	100	–	ns
$F_{I2CFCLK}$	SCL clock frequency.	–	400	KHz
I2C Standard-mode Interface				
$T_{I2CSCKL}$	SCL Low time.	4.7	–	μ s
$T_{I2CSCKH}$	SCL High time.	4.0	–	μ s
$T_{I2CSCKO}$	SDA clock to out delay.	–	3450	ns
$T_{I2CSDCK}$	SDA input setup time.	250	–	ns
$F_{I2CSCLK}$	SCL clock frequency.	–	100	KHz

Notes:

1. The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.

PS DAP Interface

Table 50: DAP Interface⁽¹⁾

Symbol	Description ⁽²⁾	Min	Max	Units
T _{PDAPDCK}	PS DAP input setup time.	3.0	–	ns
T _{PDAPCKD}	PS DAP input hold time.	2.0	–	ns
T _{PDAPCKO}	PS DAP clock to out delay.	–	10.86	ns
T _{PDAPCLK}	PS DAP clock frequency.	–	44	MHz

Notes:

- The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.
- PS DAP interface signals connect to MIO pins.

PS UART Interface

Table 51: UART Interface⁽¹⁾

Symbol	Description	Min	Max	Units
BAUD _{TXMAX}	Transmit baud rate.	–	6.25	Mb/s
BAUD _{RXMAX}	Receive baud rate.	–	6.25	Mb/s
F _{UART_REF_CLK}	UART reference clock frequency.	–	100	MHz

Notes:

- The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.

PS General Purpose I/O Interface

Table 52: General Purpose I/O (GPIO) Interface

Symbol	Description	Min	Max	Units
T _{PWGPIOH}	Input High pulse width.	10 x 1/F _{LPD_LSBUS_CTRLMAX}	–	µs
T _{PWGPIOL}	Input Low pulse width.	10 x 1/F _{LPD_LSBUS_CTRLMAX}	–	µs

PS Trace Interface

Table 53: Trace Interface⁽¹⁾

Symbol	Description	Min	Max	Units
T _{TCECKO}	Trace clock to output delay, all outputs.	–0.5	0.5	ns
T _{DCTCECLK}	Trace clock duty cycle.	45	55	%
F _{TCECLK}	Trace clock frequency.	–	125	MHz

Notes:

- The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength, fast slew rate, and a 15 pF load.

Table 63: PS-GTR Transceiver Receiver Switching Characteristics

Symbol	Description	Condition	Min	Typ	Max	Units
F _{GTRRX}	Serial data rate.		1.25	–	6	Gb/s
RX _{SST}	Receiver spread-spectrum tracking.	Modulated at 33 KHz	–5000	–	0	ppm
RX _{PPMTOL}	Data/REFCLK PPM offset tolerance.	All data rates	–350	–	350	ppm

Table 64: PCI Express Protocol Characteristics (PS-GTR Transceivers)⁽¹⁾

Standard	Description	Line Rate (Mb/s)	Min	Max	Units
PCI Express Transmitter Jitter Generation					
PCI Express Gen 1	Total transmitter jitter.	2500	–	0.25	UI
PCI Express Gen 2	Total transmitter jitter.	5000	–	0.25	UI
PCI Express Receiver High Frequency Jitter Tolerance					
PCI Express Gen 1	Total receiver jitter tolerance.	2500	0.65	–	UI
PCI Express Gen 2 ⁽²⁾	Receiver inherent timing error.	5000	0.4	–	UI
	Receiver inherent deterministic timing error.	5000	0.3	–	UI

Notes:

1. Tested per card electromechanical (CEM) methodology.
2. Between 1 MHz and 10 MHz the minimum sinusoidal jitter roll-off with a slope of 20 dB/decade.

Table 65: Serial ATA (SATA) Protocol Characteristics (PS-GTR Transceivers)

Standard	Description	Line Rate (Mb/s)	Min	Max	Units
Serial ATA Transmitter Jitter Generation					
SATA Gen 1	Total transmitter jitter.	1500	–	0.37	UI
SATA Gen 2	Total transmitter jitter.	3000	–	0.37	UI
SATA Gen 3	Total transmitter jitter.	6000	–	0.52	UI
Serial ATA Receiver High Frequency Jitter Tolerance					
SATA Gen 1	Total receiver jitter tolerance.	1500	0.27	–	UI
SATA Gen 2	Total receiver jitter tolerance.	3000	0.27	–	UI
SATA Gen 2	Total receiver jitter tolerance.	6000	0.16	–	UI

Table 66: DisplayPort Protocol Characteristics (PS-GTR Transceivers)⁽¹⁾

Standard	Description	Line Rate (Mb/s)	Min	Max	Units
DisplayPort Transmitter Jitter Generation					
RBR	Total transmitter jitter.	1620	–	0.42	UI
HBR	Total transmitter jitter.	2700	–	0.42	UI
HBR2 D10.2	Total transmitter jitter.	5400	–	0.40	UI
HBR2 CPAT	Total transmitter jitter.	5400	–	0.58	UI

Notes:

1. Only the transmitter is supported.

Programmable Logic (PL) Switching Characteristics

Table 75 (high-density IOB (HD)) and Table 76 (high-performance IOB (HP)) summarizes the values of standard-specific data input delay adjustments, output delays terminating at pads (based on standard) and 3-state delays.

- $T_{INBUF_DELAY_PAD_I}$ is the delay from IOB pad through the input buffer to the I-pin of an IOB pad. The delay varies depending on the capability of the SelectIO input buffer.
- $T_{OUTBUF_DELAY_O_PAD}$ is the delay from the O pin to the IOB pad through the output buffer of an IOB pad. The delay varies depending on the capability of the SelectIO output buffer.
- $T_{OUTBUF_DELAY_TD_PAD}$ is the delay from the T pin to the IOB pad through the output buffer of an IOB pad, when 3-state is disabled. The delay varies depending on the SelectIO capability of the output buffer. In HP I/O banks, the internal DCI termination turn-on time is always faster than $T_{OUTBUF_DELAY_TD_PAD}$ when the DCITERMDISABLE pin is used. In HD I/O banks, the on-die termination turn-on time is always faster than $T_{OUTBUF_DELAY_TD_PAD}$ when the INTERMDISABLE pin is used.

IOB High Density (HD) Switching Characteristics

Table 75: IOB High Density (HD) Switching Characteristics

I/O Standards	$T_{INBUF_DELAY_PAD_I}$					$T_{OUTBUF_DELAY_O_PAD}$					$T_{OUTBUF_DELAY_TD_PAD}$					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
DIFF_HSTL_I_18_F	0.978	0.978	1.058	0.978	1.058	1.574	1.574	1.718	1.574	1.718	1.160	1.160	1.271	1.160	1.271	ns
DIFF_HSTL_I_18_S	0.978	0.978	1.058	0.978	1.058	1.805	1.805	1.950	1.805	1.950	1.748	1.748	1.867	1.748	1.867	ns
DIFF_HSTL_I_F	0.978	0.978	1.058	0.978	1.058	1.611	1.611	1.762	1.611	1.762	1.313	1.313	1.417	1.313	1.417	ns
DIFF_HSTL_I_S	0.978	0.978	1.058	0.978	1.058	1.798	1.798	1.913	1.798	1.913	1.630	1.630	1.780	1.630	1.780	ns
DIFF_HSUL_12_F	0.911	0.911	0.977	0.911	0.977	1.573	1.573	1.703	1.573	1.703	1.222	1.222	1.335	1.222	1.335	ns
DIFF_HSUL_12_S	0.911	0.911	0.977	0.911	0.977	1.711	1.711	1.864	1.711	1.864	1.536	1.536	1.665	1.536	1.665	ns
DIFF_SSTL12_F	0.906	0.906	0.977	0.906	0.977	1.643	1.643	1.792	1.643	1.792	1.285	1.285	1.423	1.285	1.423	ns
DIFF_SSTL12_S	0.906	0.906	0.977	0.906	0.977	1.784	1.784	1.948	1.784	1.948	1.567	1.567	1.706	1.567	1.706	ns
DIFF_SSTL135_F	0.927	0.927	0.995	0.927	0.995	1.625	1.625	1.765	1.625	1.765	1.341	1.341	1.458	1.341	1.458	ns
DIFF_SSTL135_II_F	0.927	0.927	0.995	0.927	0.995	1.623	1.623	1.770	1.623	1.770	1.325	1.325	1.470	1.325	1.470	ns
DIFF_SSTL135_II_S	0.927	0.927	0.995	0.927	0.995	1.768	1.768	1.916	1.768	1.916	1.722	1.722	1.911	1.722	1.911	ns
DIFF_SSTL135_S	0.927	0.927	0.995	0.927	0.995	1.869	1.869	2.025	1.869	2.025	1.814	1.814	1.976	1.814	1.976	ns
DIFF_SSTL15_F	0.928	0.928	1.020	0.928	1.020	1.628	1.628	1.771	1.628	1.771	1.374	1.374	1.483	1.374	1.483	ns
DIFF_SSTL15_II_F	0.928	0.928	1.020	0.928	1.020	1.622	1.622	1.778	1.622	1.778	1.356	1.356	1.442	1.356	1.442	ns
DIFF_SSTL15_II_S	0.928	0.928	1.020	0.928	1.020	1.821	1.821	1.987	1.821	1.987	1.895	1.895	2.047	1.895	2.047	ns
DIFF_SSTL15_S	0.928	0.928	1.020	0.928	1.020	1.824	1.824	1.977	1.824	1.977	1.743	1.743	1.907	1.743	1.907	ns
DIFF_SSTL18_II_F	0.961	0.961	1.038	0.961	1.038	1.729	1.729	1.880	1.729	1.880	1.377	1.377	1.492	1.377	1.492	ns
DIFF_SSTL18_II_S	0.961	0.961	1.038	0.961	1.038	1.796	1.796	1.965	1.796	1.965	1.616	1.616	1.800	1.616	1.800	ns
DIFF_SSTL18_I_F	0.961	0.961	1.038	0.961	1.038	1.609	1.609	1.755	1.609	1.755	1.220	1.220	1.313	1.220	1.313	ns
DIFF_SSTL18_I_S	0.961	0.961	1.038	0.961	1.038	1.786	1.786	1.942	1.786	1.942	1.677	1.677	1.836	1.677	1.836	ns
HSTL_I_18_F	0.947	0.947	1.021	0.947	1.021	1.574	1.574	1.718	1.574	1.718	1.160	1.160	1.271	1.160	1.271	ns
HSTL_I_18_S	0.947	0.947	1.021	0.947	1.021	1.805	1.805	1.950	1.805	1.950	1.748	1.748	1.867	1.748	1.867	ns

Table 75: IOB High Density (HD) Switching Characteristics (Cont'd)

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
LVC MOS33_S_8	1.154	1.154	1.213	1.154	1.213	2.929	2.929	3.260	2.929	3.260	2.260	2.260	2.532	2.260	2.532	ns
LVDS_25	1.003	1.003	1.116	1.003	1.116	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns
LVPECL	1.003	1.003	1.116	1.003	1.116	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns
LVTTL_F_12	1.164	1.164	1.223	1.164	1.223	2.415	2.415	2.651	2.415	2.651	1.754	1.754	1.915	1.754	1.915	ns
LVTTL_F_16	1.164	1.164	1.223	1.164	1.223	2.464	2.464	2.732	2.464	2.732	1.750	1.750	1.986	1.750	1.986	ns
LVTTL_F_4	1.164	1.164	1.223	1.164	1.223	2.541	2.541	2.765	2.541	2.765	1.932	1.932	2.135	1.932	2.135	ns
LVTTL_F_8	1.164	1.164	1.223	1.164	1.223	2.582	2.582	2.787	2.582	2.787	1.910	1.910	2.063	1.910	2.063	ns
LVTTL_S_12	1.164	1.164	1.223	1.164	1.223	2.731	2.731	3.075	2.731	3.075	2.072	2.072	2.343	2.072	2.343	ns
LVTTL_S_16	1.164	1.164	1.223	1.164	1.223	2.714	2.714	3.024	2.714	3.024	2.028	2.028	2.232	2.028	2.232	ns
LVTTL_S_4	1.164	1.164	1.223	1.164	1.223	2.999	2.999	3.340	2.999	3.340	2.320	2.320	2.610	2.320	2.610	ns
LVTTL_S_8	1.164	1.164	1.223	1.164	1.223	2.929	2.929	3.260	2.929	3.260	2.260	2.260	2.532	2.260	2.532	ns
SLVS_400_25	1.020	1.020	1.136	1.020	1.136	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns
SSTL12_F	0.780	0.780	0.867	0.780	0.867	1.643	1.643	1.792	1.643	1.792	1.285	1.285	1.423	1.285	1.423	ns
SSTL12_S	0.780	0.780	0.867	0.780	0.867	1.784	1.784	1.948	1.784	1.948	1.567	1.567	1.706	1.567	1.706	ns
SSTL135_F	0.798	0.798	0.881	0.798	0.881	1.625	1.625	1.765	1.625	1.765	1.341	1.341	1.458	1.341	1.458	ns
SSTL135_II_F	0.798	0.798	0.881	0.798	0.881	1.623	1.623	1.770	1.623	1.770	1.325	1.325	1.470	1.325	1.470	ns
SSTL135_II_S	0.798	0.798	0.881	0.798	0.881	1.768	1.768	1.916	1.768	1.916	1.722	1.722	1.911	1.722	1.911	ns
SSTL135_S	0.798	0.798	0.881	0.798	0.881	1.869	1.869	2.025	1.869	2.025	1.814	1.814	1.976	1.814	1.976	ns
SSTL15_F	0.838	0.838	0.880	0.838	0.880	1.612	1.612	1.754	1.612	1.754	1.357	1.357	1.464	1.357	1.464	ns
SSTL15_II_F	0.838	0.838	0.880	0.838	0.880	1.622	1.622	1.778	1.622	1.778	1.356	1.356	1.442	1.356	1.442	ns
SSTL15_II_S	0.838	0.838	0.880	0.838	0.880	1.821	1.821	1.987	1.821	1.987	1.895	1.895	2.047	1.895	2.047	ns
SSTL15_S	0.838	0.838	0.880	0.838	0.880	1.824	1.824	1.977	1.824	1.977	1.743	1.743	1.907	1.743	1.907	ns
SSTL18_II_F	0.947	0.947	1.021	0.947	1.021	1.729	1.729	1.880	1.729	1.880	1.377	1.377	1.492	1.377	1.492	ns
SSTL18_II_S	0.947	0.947	1.021	0.947	1.021	1.796	1.796	1.965	1.796	1.965	1.616	1.616	1.800	1.616	1.800	ns
SSTL18_I_F	0.947	0.947	1.021	0.947	1.021	1.609	1.609	1.755	1.609	1.755	1.220	1.220	1.313	1.220	1.313	ns
SSTL18_I_S	0.947	0.947	1.021	0.947	1.021	1.786	1.786	1.942	1.786	1.942	1.677	1.677	1.836	1.677	1.836	ns
SUB_LVDS	1.002	1.002	1.036	1.002	1.036	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns

Table 76: IOB High Performance (HP) Switching Characteristics (Cont'd)

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
DIFF_SSTL12_F	0.394	0.394	0.402	0.394	0.402	0.412	0.412	0.430	0.412	0.430	0.538	0.538	0.566	0.538	0.566	ns
DIFF_SSTL12_M	0.394	0.394	0.402	0.394	0.402	0.553	0.553	0.584	0.553	0.584	0.641	0.641	0.676	0.641	0.676	ns
DIFF_SSTL12_S	0.394	0.394	0.402	0.394	0.402	0.758	0.758	0.808	0.758	0.808	0.823	0.823	0.879	0.823	0.879	ns
DIFF_SSTL135_DCI_F	0.371	0.371	0.402	0.371	0.402	0.411	0.411	0.428	0.411	0.428	0.537	0.537	0.565	0.537	0.565	ns
DIFF_SSTL135_DCI_M	0.371	0.371	0.402	0.371	0.402	0.551	0.551	0.582	0.551	0.582	0.645	0.645	0.685	0.645	0.685	ns
DIFF_SSTL135_DCI_S	0.371	0.371	0.402	0.371	0.402	0.746	0.746	0.799	0.746	0.799	0.829	0.829	0.893	0.829	0.893	ns
DIFF_SSTL135_F	0.375	0.375	0.402	0.375	0.402	0.408	0.408	0.428	0.408	0.428	0.528	0.528	0.561	0.528	0.561	ns
DIFF_SSTL135_M	0.375	0.375	0.402	0.375	0.402	0.555	0.555	0.585	0.555	0.585	0.641	0.641	0.679	0.641	0.679	ns
DIFF_SSTL135_S	0.375	0.375	0.402	0.375	0.402	0.772	0.772	0.823	0.772	0.823	0.827	0.827	0.878	0.827	0.878	ns
DIFF_SSTL15_DCI_F	0.397	0.397	0.417	0.397	0.417	0.412	0.412	0.429	0.412	0.429	0.531	0.531	0.563	0.531	0.563	ns
DIFF_SSTL15_DCI_M	0.397	0.397	0.417	0.397	0.417	0.553	0.553	0.583	0.553	0.583	0.645	0.645	0.685	0.645	0.685	ns
DIFF_SSTL15_DCI_S	0.397	0.397	0.417	0.397	0.417	0.768	0.768	0.822	0.768	0.822	0.847	0.847	0.912	0.847	0.912	ns
DIFF_SSTL15_F	0.404	0.404	0.417	0.404	0.417	0.424	0.424	0.445	0.424	0.445	0.551	0.551	0.577	0.551	0.577	ns
DIFF_SSTL15_M	0.404	0.404	0.417	0.404	0.417	0.554	0.554	0.585	0.554	0.585	0.639	0.639	0.677	0.639	0.677	ns
DIFF_SSTL15_S	0.404	0.404	0.417	0.404	0.417	0.767	0.767	0.817	0.767	0.817	0.813	0.813	0.867	0.813	0.867	ns
DIFF_SSTL18_I_DCI_F	0.320	0.320	0.336	0.320	0.336	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
DIFF_SSTL18_I_DCI_M	0.320	0.320	0.336	0.320	0.336	0.554	0.554	0.585	0.554	0.585	0.644	0.644	0.683	0.644	0.683	ns
DIFF_SSTL18_I_DCI_S	0.320	0.320	0.336	0.320	0.336	0.762	0.762	0.818	0.762	0.818	0.837	0.837	0.899	0.837	0.899	ns
DIFF_SSTL18_I_F	0.316	0.316	0.336	0.316	0.336	0.454	0.454	0.476	0.454	0.476	0.578	0.578	0.608	0.578	0.608	ns
DIFF_SSTL18_I_M	0.316	0.316	0.336	0.316	0.336	0.571	0.571	0.603	0.571	0.603	0.652	0.652	0.692	0.652	0.692	ns
DIFF_SSTL18_I_S	0.316	0.316	0.336	0.316	0.336	0.782	0.782	0.835	0.782	0.835	0.816	0.816	0.870	0.816	0.870	ns
HSLVDCI_15_F	0.393	0.393	0.415	0.393	0.415	0.425	0.425	0.443	0.425	0.443	0.548	0.548	0.579	0.548	0.579	ns
HSLVDCI_15_M	0.393	0.393	0.415	0.393	0.415	0.552	0.552	0.581	0.552	0.581	0.644	0.644	0.684	0.644	0.684	ns
HSLVDCI_15_S	0.393	0.393	0.415	0.393	0.415	0.748	0.748	0.802	0.748	0.802	0.827	0.827	0.890	0.827	0.890	ns
HSLVDCI_18_F	0.424	0.424	0.447	0.424	0.447	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
HSLVDCI_18_M	0.424	0.424	0.447	0.424	0.447	0.567	0.567	0.598	0.567	0.598	0.658	0.658	0.699	0.658	0.699	ns
HSLVDCI_18_S	0.424	0.424	0.447	0.424	0.447	0.761	0.761	0.817	0.761	0.817	0.836	0.836	0.900	0.836	0.900	ns
HSTL_I_12_F	0.378	0.378	0.399	0.378	0.399	0.423	0.423	0.443	0.423	0.443	0.553	0.553	0.582	0.553	0.582	ns
HSTL_I_12_M	0.378	0.378	0.399	0.378	0.399	0.551	0.551	0.582	0.551	0.582	0.642	0.642	0.679	0.642	0.679	ns
HSTL_I_12_S	0.378	0.378	0.399	0.378	0.399	0.750	0.750	0.799	0.750	0.799	0.813	0.813	0.868	0.813	0.868	ns
HSTL_I_18_F	0.322	0.322	0.339	0.322	0.339	0.456	0.456	0.474	0.456	0.474	0.576	0.576	0.606	0.576	0.606	ns
HSTL_I_18_M	0.322	0.322	0.339	0.322	0.339	0.569	0.569	0.602	0.569	0.602	0.653	0.653	0.692	0.653	0.692	ns
HSTL_I_18_S	0.322	0.322	0.339	0.322	0.339	0.781	0.781	0.833	0.781	0.833	0.816	0.816	0.871	0.816	0.871	ns
HSTL_I_DCI_12_F	0.378	0.378	0.399	0.378	0.399	0.406	0.406	0.429	0.406	0.429	0.534	0.534	0.564	0.534	0.564	ns
HSTL_I_DCI_12_M	0.378	0.378	0.399	0.378	0.399	0.556	0.556	0.586	0.556	0.586	0.654	0.654	0.694	0.654	0.694	ns
HSTL_I_DCI_12_S	0.378	0.378	0.399	0.378	0.399	0.754	0.754	0.803	0.754	0.803	0.842	0.842	0.907	0.842	0.907	ns
HSTL_I_DCI_18_F	0.321	0.321	0.339	0.321	0.339	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
HSTL_I_DCI_18_M	0.321	0.321	0.339	0.321	0.339	0.554	0.554	0.585	0.554	0.585	0.643	0.643	0.684	0.643	0.684	ns
HSTL_I_DCI_18_S	0.321	0.321	0.339	0.321	0.339	0.761	0.761	0.817	0.761	0.817	0.836	0.836	0.900	0.836	0.900	ns
HSTL_I_DCI_F	0.393	0.393	0.415	0.393	0.415	0.431	0.431	0.445	0.431	0.445	0.555	0.555	0.575	0.555	0.575	ns
HSTL_I_DCI_M	0.393	0.393	0.415	0.393	0.415	0.552	0.552	0.581	0.552	0.581	0.644	0.644	0.684	0.644	0.684	ns

Block RAM and FIFO Switching Characteristics

Table 80: Block RAM and FIFO Switching Characteristics

Symbol	Description	Speed Grade and V_{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
Maximum Frequency							
$F_{MAX_WF_NC}$	Block RAM (WRITE_FIRST and NO_CHANGE modes).	825	738	645	585	516	MHz
F_{MAX_RF}	Block RAM (READ_FIRST mode).	718	637	575	510	460	MHz
F_{MAX_FIFO}	FIFO in all modes without ECC.	825	738	645	585	516	MHz
F_{MAX_ECC}	Block RAM and FIFO in ECC configuration without PIPELINE.	718	637	575	510	460	MHz
	Block RAM and FIFO in ECC configuration with PIPELINE and Block RAM in WRITE_FIRST or NO_CHANGE mode.	825	738	645	585	516	MHz
$T_{PW}^{(1)}$	Minimum pulse width.	495	542	543	577	578	ps
Block RAM and FIFO Clock-to-Out Delays							
T_{RCKO_DO}	Clock CLK to DOUT output (without output register).	0.91	1.02	1.11	1.46	1.53	ns, Max
$T_{RCKO_DO_REG}$	Clock CLK to DOUT output (with output register).	0.27	0.29	0.30	0.42	0.44	ns, Max

Notes:

1. The MMCM and PLL DUTY_CYCLE attribute should be set to 50% to meet the pulse-width requirements at the higher frequencies.

Table 91: Global Clock Input Setup and Hold With MMCM

Symbol	Description	Device	Speed Grade and V _{CCIINT} Operating Voltages					Units	
			0.90V	0.85V		0.72V			
			-3	-2	-1	-2	-1		
Input Setup and Hold Time Relative to Global Clock Input Signal using SSTL15 Standard. (1)(2)(3)									
T _{PSMMCMCC_ZU2}	Global clock input and input flip-flop (or latch) with MMCM.	Setup	XCZU2	N/A	1.83	1.96	2.29	2.48	ns
T _{PHMMCMCC_ZU2}		Hold			-0.19	-0.19	0.13	0.13	ns
T _{PSMMCMCC_ZU3}		Setup	XCZU3	N/A	1.83	1.96	2.29	2.48	ns
T _{PHMMCMCC_ZU3}		Hold			-0.19	-0.19	0.13	0.13	ns
T _{PSMMCMCC_ZU4}		Setup	XCZU4	1.96	1.96	2.10	2.49	2.59	ns
T _{PHMMCMCC_ZU4}		Hold			-0.12	-0.12	-0.12	0.27	0.48
T _{PSMMCMCC_ZU5}		Setup	XCZU5	1.96	1.96	2.10	2.49	2.59	ns
T _{PHMMCMCC_ZU5}		Hold			-0.12	-0.12	-0.12	0.27	0.48
T _{PSMMCMCC_ZU6}		Setup	XCZU6	1.97	2.00	2.12	2.26	2.44	ns
T _{PHMMCMCC_ZU6}		Hold			-0.11	-0.11	-0.11	0.16	0.18
T _{PSMMCMCC_ZU7}		Setup	XCZU7	1.91	1.91	2.02	2.45	2.70	ns
T _{PHMMCMCC_ZU7}		Hold			-0.14	-0.14	-0.14	0.37	0.38
T _{PSMMCMCC_ZU9}		Setup	XCZU9	1.97	2.00	2.12	2.26	2.44	ns
T _{PHMMCMCC_ZU9}		Hold			-0.11	-0.11	-0.11	0.16	0.18
T _{PSMMCMCC_ZU11}		Setup	XCZU11	2.08	2.08	2.23	2.59	2.75	ns
T _{PHMMCMCC_ZU11}		Hold			-0.08	-0.08	0.04	0.35	0.74
T _{PSMMCMCC_ZU15}		Setup	XCZU15	1.96	1.99	2.12	2.26	2.44	ns
T _{PHMMCMCC_ZU15}		Hold			-0.10	-0.10	-0.10	0.17	0.19
T _{PSMMCMCC_ZU17}		Setup	XCZU17	1.89	1.89	2.03	2.36	2.55	ns
T _{PHMMCMCC_ZU17}		Hold			-0.16	-0.16	-0.16	0.31	0.34
T _{PSMMCMCC_ZU19}	Setup	XCZU19	1.89	1.89	2.03	2.36	2.55	ns	
T _{PHMMCMCC_ZU19}	Hold			-0.16	-0.16	-0.16	0.31	0.34	ns

Notes:

1. Setup and hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the global clock input signal using the slowest process, slowest temperature, and slowest voltage. Hold time is measured relative to the global clock input signal using the fastest process, fastest temperature, and fastest voltage.
2. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible I/O and CLB flip-flops are clocked by the global clock net.
3. Use IBIS to determine any duty-cycle distortion incurred using various standards.

Package Parameter Guidelines

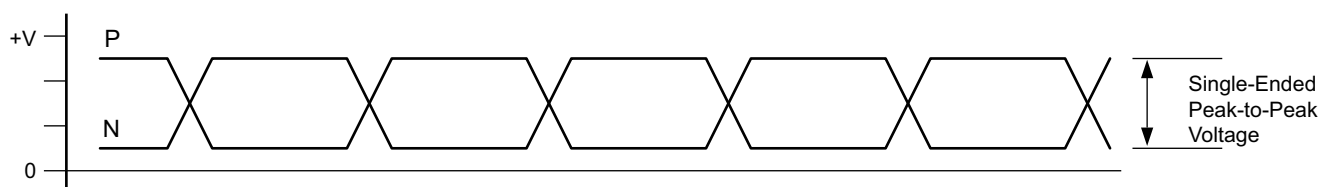
The parameters in this section provide the necessary values for calculating timing budgets for clock transmitter and receiver data-valid windows.

Table 93: Package Skew

Symbol	Description	Device	Package	Value	Units
PKGSKEW	Package Skew	XCZU2	SBVA484	105	ps
			SFVA625	108	ps
			SFVC784	93	ps
		XCZU3	SBVA484	105	ps
			SFVA625	108	ps
			SFVC784	93	ps
		XCZU4	SFVC784		ps
			FBVB900		ps
		XCZU5	SFVC784		ps
			FBVB900		ps
		XCZU6	FFVC900	119	ps
			FFVB1156	134	ps
		XCZU7	FBVB900	141	ps
			FFVC1156	175	ps
			FFVF1517	305	ps
		XCZU9	FFVC900	119	ps
			FFVB1156	134	ps
		XCZU11	FFVC1156		ps
			FFVB1517		ps
			FFVF1517		ps
			FFVC1760	215	ps
		XCZU15	FFVC900	118	ps
			FFVB1156	132	ps
		XCZU17	FFVB1517	221	ps
FFVC1760	226		ps		
FFVD1760	178		ps		
FFVE1924	174		ps		
XCZU19	FFVB1517	221	ps		
	FFVC1760	226	ps		
	FFVD1760	178	ps		
	FFVE1924	174	ps		

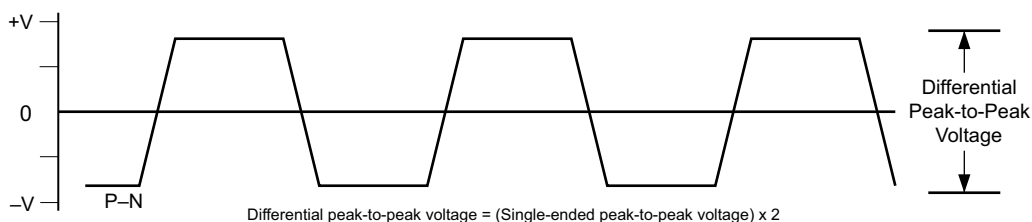
Notes:

1. These values represent the worst-case skew between any two SelectIO resources in the package: shortest delay to longest delay from die pad to ball.
2. Package delay information is available for these device/package combinations. This information can be used to deskew the package.



X16653-101316

Figure 5: Single-Ended Peak-to-Peak Voltage



X16639-101316

Figure 6: Differential Peak-to-Peak Voltage

Table 107 and Table 108 summarize the DC specifications of the clock input of the GTY transceivers in Zynq UltraScale+ MPSoCs. Consult the *UltraScale Architecture GTY Transceiver User Guide* (UG578) for further details.

Table 107: GTY Transceiver Clock DC Input Level Specification

Symbol	DC Parameter	Min	Typ	Max	Units
V_{IDIFF}	Differential peak-to-peak input voltage	250	–	2000	mV
R_{IN}	Differential input resistance	–	100	–	Ω
C_{EXT}	Required external AC coupling capacitor	–	10	–	nF

Table 108: GTY Transceiver Clock Output Level Specification

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{OL}	Output Low voltage for P and N	$R_T = 100\Omega$ across P and N signals	100	–	330	mV
V_{OH}	Output High voltage for P and N	$R_T = 100\Omega$ across P and N signals	500	–	700	mV
V_{DDOUT}	Differential output voltage (P–N), P = High (N–P), N = High	$R_T = 100\Omega$ across P and N signals	300	–	430	mV
V_{CMOUT}	Common mode voltage	$R_T = 100\Omega$ across P and N signals	300	–	500	mV

Table 114: GTY Transceiver User Clock Switching Characteristics⁽¹⁾ (Cont'd)

Symbol	Description	Data Width Conditions (Bit)		Speed Grade and V _{CCINT} Operating Voltages					Units
				0.90V		0.85V		0.72V	
		Internal Logic	Interconnect Logic	-3 ⁽²⁾	-2 ⁽²⁾⁽³⁾	-1 ⁽⁴⁾⁽⁵⁾	-2 ⁽³⁾	-1 ⁽⁵⁾	
F _{TXIN2}	TXUSRCLK2 ⁽⁶⁾ maximum frequency	16	16	511.719	511.719	390.625	390.625	322.266	MHz
		16	32	255.859	255.859	195.313	195.313	161.133	MHz
		32	32	511.719	511.719	390.625	390.625	322.266	MHz
		32	64	255.859	255.859	195.313	195.313	161.133	MHz
		64	64	511.719	440.781	402.832	402.832	195.313	MHz
		64	128	255.859	220.391	201.416	201.416	97.656	MHz
		20	20	409.375	409.375	312.500	312.500	257.813	MHz
		20	40	204.688	204.688	156.250	156.250	128.906	MHz
		40	40	409.375	409.375	312.500	350.000	257.813	MHz
		40	80	204.688	204.688	156.250	175.000	128.906	MHz
		80	80	409.375	352.625	322.266	352.625	156.250	MHz
80	160	204.688	176.313	161.133	176.313	78.125	MHz		
F _{RXIN2}	RXUSRCLK2 ⁽⁶⁾ maximum frequency	16	16	511.719	511.719	390.625	390.625	322.266	MHz
		16	32	255.859	255.859	195.313	195.313	161.133	MHz
		32	32	511.719	511.719	390.625	390.625	322.266	MHz
		32	64	255.859	255.859	195.313	195.313	161.133	MHz
		64	64	511.719	440.781	402.832	402.832	195.313	MHz
		64	128	255.859	220.391	201.416	201.416	97.656	MHz
		20	20	409.375	409.375	312.500	312.500	257.813	MHz
		20	40	204.688	204.688	156.250	156.250	128.906	MHz
		40	40	409.375	409.375	312.500	350.000	257.813	MHz
		40	80	204.688	204.688	156.250	175.000	128.906	MHz
		80	80	409.375	352.625	322.266	352.625	156.250	MHz
80	160	204.688	176.313	161.133	176.313	78.125	MHz		

Notes:

1. Clocking must be implemented as described in the *UltraScale Architecture GTY Transceiver User Guide* ([UG578](#)).
2. For speed grades -3E, -2E, and -2I, a 16-bit and 20-bit internal data path can only be used for line rates less than 8.1875 Gb/s.
3. For speed grade -2LE, a 16-bit and 20-bit internal data path can only be used for line rates less than 8.1875 Gb/s when V_{CCINT} = 0.85V or 6.25 Gb/s when V_{CCINT} = 0.72V.
4. For speed grades -1E and -1I, a 16-bit and 20-bit internal data path can only be used for line rates less than 6.25 Gb/s.
5. For speed grade -1LI, a 16-bit and 20-bit internal data path can only be used for line rates less than 6.25 Gb/s when V_{CCINT} = 0.85V or 5.15625 Gb/s when V_{CCINT} = 0.72V.
6. When the gearbox is used, these maximums refer to the XCLK. For more information, see the *Valid Data Width Combinations for TX Asynchronous Gearbox* table in the *UltraScale Architecture GTY Transceiver User Guide* ([UG578](#)).

Integrated Interface Block for Interlaken

More information and documentation on solutions using the integrated interface block for Interlaken can be found at [UltraScale+ Interlaken](#). The *UltraScale Architecture and Product Overview (DS890)* lists how many blocks are in each Zynq UltraScale+ MPSoC. This section describes the following Interlaken configurations.

- 12 x 12.5 Gb/s protocol and lane logic mode ([Table 118](#)).
- 6 x 25.78125 Gb/s and 6 x 28.21 Gb/s protocol and lane logic mode ([Table 119](#)).
- 12 x 25.78125 Gb/s lane logic only mode ([Table 120](#)).

Zynq UltraScale+ MPSoCs in the SFVB784, FFVA676, and FFVA1156 packages are only supported using the 12 x 12.5 Gb/s Interlaken configuration. See [Table 109](#) for the F_{GTYMAX} description.

Table 118: Maximum Performance for Interlaken 12 x 12.5 Gb/s Protocol and Lane Logic Mode Designs

Symbol	Description	Speed Grade and V_{CCINT} Operating Voltages										Units
		0.90V		0.85V				0.72V				
		-3	-2	-1	-2	-1	-2	-1	-2	-1		
$F_{RX_SERDES_CLK}$	Receive serializer/deserializer clock	195.32		195.32				195.32				MHz
$F_{TX_SERDES_CLK}$	Transmit serializer/deserializer clock	195.32		195.32				195.32				MHz
F_{DRP_CLK}	Dynamic reconfiguration port clock	250.00		250.00				250.00				MHz
		Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	
F_{CORE_CLK}	Interlaken core clock	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	MHz
F_{LBUS_CLK}	Interlaken local bus clock	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	MHz

Notes:

1. These are the minimum clock frequencies at the maximum lane performance.

Video Codec Performance

The *UltraScale Architecture and Product Overview* ([DS890](#)) lists the Zynq UltraScale+ MPSoC EV devices that include the Video Codec unit (VCU).

Table 123: VCU Performance

Description	Speed Grade and V _{CCINT} Operating Voltages					Units
	0.90V	0.85V		0.72V		
	-3	-2	-1	-2	-1	
Video Codec decoder block maximum frequency (H.264/5 10-bit 4:2:2)	667	667	667	667	667	MHz

PL System Monitor Specifications

Table 124: PL SYSMON Specifications

Parameter	Symbol	Comments/Conditions	Min	Typ	Max	Units
V _{CCADC} = 1.8V ±3%, V _{REFP} = 1.25V, V _{REFN} = 0V, ADCCLK = 5.2 MHz, T _j = -40°C to 100°C, typical values at T _j = 40°C						
ADC Accuracy⁽¹⁾						
Resolution			10	–	–	Bits
Integral nonlinearity ⁽²⁾	INL		–	–	±1.5	LSBs
Differential nonlinearity	DNL	No missing codes, guaranteed monotonic	–	–	±1	LSBs
Offset error		Offset calibration enabled	–	–	±2	LSBs
Gain error			–	–	±0.4	%
Sample rate			–	–	0.2	MS/s
RMS code noise		External 1.25V reference	–	–	1	LSBs
		On-chip reference	–	1	–	LSBs
ADC Accuracy at Extended Temperatures						
Resolution		T _j = -55°C to 125°C	10	–	–	Bits
Integral nonlinearity ⁽²⁾	INL	T _j = -55°C to 125°C	–	–	±1.5	LSBs
Differential nonlinearity	DNL	No missing codes, guaranteed monotonic (T _j = -55°C to 125°C)	–	–	±1	
Analog Inputs⁽²⁾						
ADC input ranges		Unipolar operation	0	–	1	V
		Bipolar operation	-0.5	–	+0.5	V
		Unipolar common mode range (FS input)	0	–	+0.5	V
		Bipolar common mode range (FS input)	+0.5	–	+0.6	V
Maximum external channel input ranges		Adjacent channels set within these ranges should not corrupt measurements on adjacent channels	-0.1	–	V _{CCADC}	V